Product/Process Change Notice - PCN 21_0201 Rev. -

Analog Devices, Inc. One Analog Way, Wilmington, MA 01887

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title:	LTM4633/LTM4634 Notification of Qualification of New Mold Compound and Substrate Change
Publication Date:	10-Sep-2021
Effectivity Date:	13-Dec-2021 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release: LTM4633/LTM4634 Substrate change and mold compound change

Description Of Change:

- A new mold compound has been qualified in LTM4633/LTM4634 which is the next generation mold compound going forward. The new mold compound uses fine filler and facilitates the filling of tighter spaces.
- A new Substrate Design revision and substrate material have been qualified for LTM4633/LTM4634. The new substrate will be in use going forward.

Reason For Change:

- Higher density component assembly in a µModule substrate requires mold filling in tighter spaces between and underneath components. The new mold compound facilitates this task which also improves assembly yield.
- Substrate Design revision to improve the visual outlook of the product.

Impact of the change (positive or negative) on fit, form, function & reliability:

The change is transparent in customer applications since there is no change in the form, fit, function, quality, or reliability of the products. The product datasheet is unchanged.

Product Identification *(this section will describe how to identify the changed material)*

Production shipment of the product incorporating the new material will begin no sooner than the effective date.

Summary of Supporting Information:

The qualification has been performed per Industry Standard Test Methods. See attached Qualification Results Summary.

Supporting Documents

Attachment 1: Type: Qualification Results Summary

ADI_PCN_21_0201_Rev_-_ADI_PCN_LTM4633_LTM4634.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	**Europe:**	**Japan:**	**Rest of Asia:**
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_ROA@analog.com

Appendix A - Affected ADI Models				
Added Parts On This Revision - Product Family / Model Number (11)				
LTM4633 / LTM4633EY#PBF	LTM4633 / LTM4633IY	LTM4633 / LTM4633IY#2KDPBF	LTM4633 / LTM4633IY#PBF	LTM4633 / LTM4633MPY
LTM4633 / LTM4633MPY#PBF	LTM4634 / LTM4634EY#2KEPBF	LTM4634 / LTM4634EY#PBF	LTM4634 / LTM4634IY	LTM4634 / LTM4634IY#2KEPBF
LTM4634 / LTM4634IY#PBF				

Appendix B - Revision History			
Rev	**Publish Date**	**Effectivity Date**	**Rev Description**
Rev. -	10-Sep-2021	13-Dec-2021	Initial Release: LTM4633/LTM4634 Substrate change and mold compound change

Qualification Results Summary of LTM4633, LTM4634 with revised substrate and Sumitomo G311E mold compound

QUALIFICATION STATUS – LTM4633 BGA			
TEST	**SPECIFICATION**	**SAMPLE SIZE**	**RESULTS**
Thermal Shock (TS)*	JEDEC *JESD22-A106*	**1*200**	**Pass**
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	**1*200**	**Pass**

*Preconditioned per JEDEC/IPC J-STD-020 MSL3 (@245C)

Qualification Results Summary of LTM4633, LTM4634 with revised substrate and Sumitomo G311E mold compound

QUALIFICATION STATUS – LTM4634 BGA			
TEST	**SPECIFICATION**	**SAMPLE SIZE**	**RESULTS**
Unbiased Highly Accelerated Stress Test (UHAST)*	JEDEC *JESD22-A102*	**1*77**	**Pass**
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	**1*77**	**Pass**
Thermal Shock (TS)*	JEDEC *JESD22-A106*	**1*77**	**Pass**
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	**1*231**	**Pass**

*Preconditioned per JEDEC/IPC J-STD-020 MSL3 (@245C)